



Attorney's Docket No.: 082225.P1423D

#10/c
12/12/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for:

Chung Lam

Serial No.: 09/336,116

Filed: June 18, 1999

For: **BOARD LEVEL DECAPSULATOR**

Examiner: Ahmed, S.

Art Group: 1746

AMENDMENT AND RESPONSE TO OFFICE ACTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed September 3, 2002, Applicant respectfully requests consideration in view of the following amendments and remarks:

IN THE CLAIMS

5b D1
9. (Twice Amended) A method for decapsulating installed integrated circuit (IC) packages, comprising:

C1
receiving an IC package, permanently installed onto a printed circuit board;
placing the installed IC package onto a tray;
clamping an injection head onto the installed IC package; and,
spraying decapsulation fluid onto the installed IC package through the injection head.

C2
10. (Twice Amended) The method as recited in claim 9, further comprising:
moving a stub that is plugged into the tray and which supports the printed circuit board of the installed IC package before the installed IC package is placed onto said tray.

C3
11. (Amended) The method as recited in claim 9, further comprising:
controlling a flow of the decapsulation fluid through a pair of tubes that couple an extender to the injection head using a corresponding pair of valves.